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## Chapter 1 Target Devices

The target devices the CC-RL supports are listed on the Website.

Please see the URL below.

CS+ Product Page:

<http://www.renesas.com/cs+>

## Chapter 2 User's Manuals

Please read the following user's manuals along with this document.

Manual Name	Document Number
CC-RL Compiler	R20UT3123EJ0103
CS+ CC-RL Build Tool Operation	R20UT3284EJ0102

## Chapter 3 Keywords When Uninstalling the Product

There are two ways to uninstall this product.

- Use the integrated uninstaller from Renesas (uninstalls all CS+ components)
- Use the Windows uninstaller (only uninstalls this product)

To use the Windows uninstaller, select "CS+ CC-RL V1.03.00" from "Programs and Features" of the control panel.

## Chapter 4 Changes

This chapter describes changes to V1.03.00 of the CC-RL compiler.

### 4.1 Changes to V1.03.00 of the CC-RL Compiler

This section describes the changes in CC-RL from V1.02.00 to V1.03.00. Note that the features which are only available to users holding a registered license for the Professional edition are indicated as **[Professional edition]**.

#### 4.1.1 Enhanced optimization

For V1.03.00, optimization has been further enhanced on points (1) to (4), listed and described below.

- (1) Merging of stack areas allocated for auto arrays in different local scopes (reducing the stack size)

The compiler merges stack areas allocated for auto arrays that belong to different blocks ({}), whose lifetimes do not overlap.

<Example of source code>

```
int *g;
void func01(void)
{
    {
        int array01[10];
        g = array01;
        foo();
    }
    {
        int array02[10];    // Lifetimes of array01[10] and
                          // array02[10] do not overlap.

        g = array02+2;
    }
}
```

<Code generated by V1.02.00>

```
_func01:
    .STACK_func01 = 44    ; Size of allocated stack =44byte
    subw sp, #0x28
    movw ax, sp
    movw !LOWW(_g), ax
    call !!_foo
    movw ax, sp
    addw ax, #0x0018
    movw !LOWW(_g), ax
    addw sp, #0x28
    ret
```

```

<Code generated by V1.03.00>
_func01:
    .STACK_func01 = 24      ; Size of allocated stack =24byte
    subw sp, #0x14
    movw ax, sp
    movw !LOWW(_g), ax
    call !!_foo
    movw ax, sp
    addw ax, #0x0004
    movw !LOWW(_g), ax
    addw sp, #0x14
    ret

```

## (2) Optimization of constant propagation

Obviously recognizable calculations of constants within loops are omitted.

```

<Example of source code>
int func02(int xtra, int n4, int e1[]) {
    int i,ix,j,k,l;
    j = 1;
    k = 2;
    l = 3;

    for (ix=0; ix<xtra; ix++) {
        for (i=0; i<n4; i++) {
            j = j*(k-j)*(l-k);    // j is always 1
            k = l*k-(l-j)*k;      // k is always 2
            l = (l-k)*(k+j);      // l is always 3
            e1[l-2] = j+k+l;      // l-2 is always 1, j+k+l is always 6
            e1[k-2] = j*k*l;      // k-2 is always 0, j+k*l is always 6
        }
    }
    return e1[0]+e1[1];
}

```

```

<Code generated by V1.02.00 (1/3)>
.BB@LABEL@1_3:      ; bb49
    movw ax, [sp+0x0E]
    xor a, #0x80
    movw [sp+0x0A], ax
    movw ax, hl
    movw hl, sp
    xor a, #0x80
    cmpw ax, [hl+0x0A]
    bnc $.BB@LABEL@1_5
.BB@LABEL@1_4:      ; bb1
                    ; j*(k-j)*(l-k) and
                    ; l*k-(l-j)*k, (l-k)*(k+j) are calculated each time.

    movw ax, [hl]
    subw ax, bc
    movw bc, ax
    movw ax, [sp+0x04]
    movw hl, ax
    mulh
    movw [sp+0x04], ax
    movw ax, [sp+0x02]

```

<Code generated by V1.02.00 (2/3)>

```
subw ax, hl
movw bc, ax
movw ax, [sp+0x04]
mulh
movw hl, ax
movw [sp+0x04], ax
pop bc
push bc
movw ax, [sp+0x02]
mulh
movw [sp+0x0A], ax
movw ax, [sp+0x02]
movw bc, ax
movw ax, [sp+0x00]
subw ax, hl
mulh
movw bc, ax
movw ax, [sp+0x0A]
subw ax, bc
movw [sp+0x02], ax
addw ax, hl
movw [sp+0x0A], ax
movw hl, sp
movw bc, ax
movw ax, [hl]
subw ax, [hl+0x02]
mulh
movw bc, ax
movw [hl], ax
movw ax, bc
addw ax, ax
addw ax, de
addw ax, #0xFFFC
movw hl, ax
movw ax, [sp+0x0A]
addw ax, bc
movw [hl], ax
movw ax, [sp+0x04]
movw bc, ax
movw ax, [sp+0x02]
movw hl, ax
mulh
movw [sp+0x0A], ax
pop bc
push bc
movw ax, [sp+0x0A]
mulh
movw bc, ax
movw ax, hl
addw ax, ax
addw ax, de
addw ax, #0xFFFC
movw hl, ax
movw ax, bc
movw [hl], ax
movw ax, [sp+0x06]
movw hl, ax
```

```
<Code generated by V1.02.00 (3/3)>
incw hl
movw ax, hl
movw [sp+0x06], ax
movw ax, [sp+0x02]
movw bc, ax
movw [sp+0x02], ax
br $.BB@LABEL@1_3
```

```
<Code generated by V1.03.00>
.BB@LABEL@1_3:          ; bb48
    movw ax, [sp+0x04]
    xor a, #0x80
    movw hl, ax
    movw ax, bc
    xor a, #0x80
    cmpw ax, hl
    bnc $.BB@LABEL@1_5
.BB@LABEL@1_4:          ; bb1
    ; 6 is always assigned to e1[1].
    ; 6 is always assigned to e1[0].

    movw ax, #0x0006
    movw [de+0x02], ax
    movw [de], ax
    incw bc
    br $.BB@LABEL@1_3
```

### (3) Optimization of induction variables

The compiler does not generate code for redundantly updating loop induction variables.

```
<Example of source code>
void callee(unsigned i);
void caller(void){
    unsigned i;
    for(i=128; i != 0; --i){
        callee(i);
    }
}
```

```
<Code generated by V1.02.00 (1/2)>
_caller:
    .STACK_caller = 8
    subw sp, #0x04
    movw ax, #0x0080
    movw [sp+0x02], ax
    movw [sp+0x00], ax; Loop induction variable
    ; is redundantly initialized.
.BB@LABEL@1_1:          ; bb
    call !!_callee
    movw ax, [sp+0x02]
    addw ax, #0xFFFF
    movw [sp+0x02], ax
    movw ax, [sp+0x00]; Loop induction variable
    ; is redundantly initialized.
```



```
<Code generated by V1.02.00 (2/2)>
    decw ax
    movw [sp+0x00], ax
    bnz $.BB@LABEL@1_1
.BB@LABEL@1_2:      ; return
    addw sp, #0x04
    ret
```

```
<Code generated by V1.03.00>
_caller:
    .STACK_caller = 6
    push hl
    movw ax, #0x0080
    movw [sp+0x00], ax
.BB@LABEL@1_1:      ; bb
    call !!_callee
    movw ax, [sp+0x00]
    addw ax, #0xFFFF
    movw [sp+0x00], ax
    bnz $.BB@LABEL@1_1
.BB@LABEL@1_2:      ; return
    pop hl
    ret
```

#### (4) Deleting unused code

The ability to delete unused code has been further enhanced.

```
<Example of source code>
unsigned long test(unsigned long long variable, int var) {
    if (var) {
        variable &= 0x012345678abcdefULL;
    }
    return (variable >> 32);
}
```

```
<Code generated by V1.02.00 (1/2)>
_test:
    .STACK_test = 4
    or a, x
    movw ax, [sp+0x0A]
    movw bc, ax
    movw ax, [sp+0x08]
    movw de, ax
    movw ax, [sp+0x06]
    movw hl, ax
    movw ax, [sp+0x04]
    bz $.BB@LABEL@1_2
.BB@LABEL@1_1:      ; if_then_bb
    and a, #0xCD      ;ax([sp+4]) is not referenced
                    ; in the subsequent lines.

    xch a, x          ;
    and a, #0xEF      ;
    xch a, x          ;
    movw ax, hl       ;hl([sp+6]) is not referenced
                    ; in the subsequent lines.
```

```
<Code generated by V1.02.00 (2/2)>
```

```
    and a, #0x78      ;
    xch a, x          ;
    and a, #0xAB     ;
    xch a, x          ;
    movw ax, de
    and a, #0x34
    xch a, x
    and a, #0x56
    xch a, x
    movw de, ax
    movw ax, bc
    clrb a
    xch a, x
    and a, #0x12
    xch a, x
    movw bc, ax
.BB@LABEL@1_2:      ; if_break_bb
    movw ax, de
    ret
```

```
<Code generated by V1.03.00>
```

```
_test:
    .STACK_test = 4
    or a, x
    movw ax, [sp+0x0A]
    movw bc, ax
    movw ax, [sp+0x08]
    movw de, ax
    bz $.BB@LABEL@1_2
.BB@LABEL@1_1:      ; if_then_bb
    and a, #0x34
    xch a, x
    and a, #0x56
    xch a, x
    movw de, ax
    movw ax, bc
    clrb a
    xch a, x
    and a, #0x12
    xch a, x
    movw bc, ax
.BB@LABEL@1_2:      ; if_break_bb
    movw ax, de
    ret
```

#### 4.1.2 Improvements to the feature for checking source code against MISRA-C:2012 rules [Professional edition]

The following rule numbers have been added to those which can be designated as arguments of the -misra2012 option, which selects checking by the compiler of source code against the specified MISRA-C:2012 rules.

2.6 2.7

9.2 9.3

12.1 12.3 12.4

14.4

15.1 15.2 15.3 15.4 15.5 15.6 15.7

16.1 16.2 16.3 16.4 16.5 16.6 16.7

17.1 17.7

18.4 18.5

19.2

20.1 20.2 20.3 20.4 20.5 20.6 20.7 20.8 20.9 20.10 20.11 20.12 20.13 20.14

The following are the numbers of MISRA-C:2012 rules against which the V1.02.00 and V1.03.00 compilers can check source code for compliance.

<i>Rule classification (number of rules in the standard)</i>	<i>V1.02.00</i>	<i>V1.03.00</i>
Mandatory rules (10)	3	3
Required rules (101)	31	<b>58</b>
Advisory rules (32)	7	<b>21</b>
<b>Total number of rules (143)</b>	<b>41</b>	<b>82</b>

#### 4.1.3 Enhancing the security of dynamic memory management [Professional edition]

A feature has been added for the detection of illicit operations in the release of heap space. This feature can be used by linking a dedicated standard library of secure functions related to dynamic memory allocation.

An error with code E0562310 will occur if the compiler is not registered for a license to the Professional edition.

Run the dedicated standard library as follows.

- (1) As well as the actual areas allocated for users in the heap space by the calloc, malloc, and realloc functions, two extra bytes for use in the detection of illicit operations are added before and after each area, for a total of four added bytes.

- (2) When called, the free and realloc functions determine if any of (a) to (c) applies.
  - (a) The argument is not a pointer to an actual area allocated by calloc, malloc, or realloc.
  - (b) The pointer is to an area that has already been released.
  - (c) Neither of the two two-byte margins for detecting illicit operations has been overwritten.
- (3) In the event of any of the above, an illicit operation is assumed to have proceeded, and `_heap_chk_fail` will be called.

The user must write the `__heap_chk_fail` function. Write the processing which should be executed when any illicit operation has been detected in the heap space. For example, if either of the two two-byte margins for detecting illicit operations has been overwritten in the 6th line in the following program, `_heap_chk_fail` will be executed when the related heap space is released by the 8th line.

```
1: #include <string.h>
2: #include <stdlib.h>
3: void func(char *str) {
4:   char *buf;
5:   buf = malloc(4);
6:   strcpy(buf, str); // The heap space will be corrupted depending
   on the length of str
7:
8:   free(buf);
9: }
```

By using this feature, you can easily counter security problems through measures against the dual release of memory and against buffers overflowing.

#### 4.1.4 Addition of the `-Opipeline` option

The `-Opipeline` option for pipeline optimization has been added.

#### 4.1.5 Addition of intrinsic functions for bit manipulation

Intrinsic functions `__set1`, `__clr1`, and `__not1` for bit manipulation have been added.

#### 4.1.6 Rectified points for caution

Points for caution on the following two items no longer apply.

- External labels defined after conditional assembly control instructions (CCRL#006)
- Designating a member of a packed structure or union in an initializing declaration (CCRL#007)
- Writing an instruction operand in ways which are not included in the list of instruction operations (CCRL#008)
- Outputting code which overwrites a register for interrupt handlers (CCRL#009)

- Scope of optimization (CCRL#010)

#### 4.1.7 Other changes and improvements

Other major changes and improvements are described below.

- (a) Improved debugging information

A problem with C and assembly source code not being displayed properly during debugging has been corrected.

- (b) Improved prevention of internal errors

A problem with an internal error during building has been corrected.

## Chapter 5 Points for Caution

Please refer to the user's manual for caution regarding V1.03.00 of the CC-RL compiler.

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